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# Aehr Test Systems Announces $1.7 Million Follow-On Order for ABTS™ Burn-in and Test Systems from Leading IC Manufacturer

**Fremont, CA (June 25, 2015) - Aehr Test Systems** (**NASDAQ: AEHR**), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received a $1.7 million follow-on order for its Advanced Burn-in and Test Systems (ABTS) from a leading multi-national manufacturer of advanced logic integrated circuits (ICs) for automotive, embedded processing, digital signal processing and analog applications. The order includes prepayments in order to lock in short lead times and special pricing, and the systems are expected to ship within the next six months.

“We are pleased to receive this follow-on order for additional systems,” said Mark Allison, vice president of sales at Aehr Test Systems. “The customer is running at full capacity in their production burn-in and test area and needed to add capacity quickly due to increasing demand for their advanced automotive devices. The ABTS systems, with their individual temperature control capability for high-power devices, are a key part of the customer’s quality and reliability program for their expanding line of automotive products.”

“Automobiles are making increasing use of infotainment, safety and communications systems,” said Carl Buck, vice president of marketing at Aehr Test. “These systems consist of a range of electronic functions from sensing, through conversion and transmission to high-performance processing, requiring the full spectrum of analog and embedded processing ICs. For example, Advanced Driver Assistance Systems employ processors and sensors which enable multiple vision and radar systems for applications such as lane departure warning, rearview and surroundview camera systems, and collision warning and avoidance as well as blind spot detection. The manufacturers of the components of these systems are required to meet the exacting quality and reliability standards of the automotive market. Our systems provide our customers with the ability to screen out devices with latent defects in order to meet those stringent reliability requirements.”

The ABTS family of products is based on a new hardware and software platform that is designed to address not only today’s devices, but also future devices for many years to come. It can test and burn-in both logic and memory devices, including resources for high pin-count devices and configurations for high-power and low-power applications. ABTS systems can be configured with up to 72 burn-in boards, up to 320 I/O channels, 32M of test vector memory per channel and up to 16 independent device power supplies. The ABTS system is optimized for use with the Sensata iSocket* Thermal Management Technology, which provides a scalable cost-effective solution using individual device temperature control for up to 64 devices per burn-in board and up to 75 watts per device or more. Individual temperature control enables high-power devices with a broad range of power dissipation to be burned-in simultaneously in a single burn-in chamber while maintaining a

precise device temperature. The ABTS system also uses N+1 redundancy technology for many key components in the system to maximize system uptime.

*iSocket is a trademark of Sensata Technologies, Inc.

**About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOX™ families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both low-power and high-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit Aehr Test's website at www.aehr.com.

**Safe Harbor Statement**

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding expected shipping dates of our ABTS systems and uses of our ABTS systems. The risks and uncertainties that could cause our results to differ materially from those expressed or implied by such forward-looking statements include, without limitation, general world economic conditions and events, the state of the semiconductor equipment market, our ability to maintain sufficient cash to support operations, acceptance by customers of the ABTS technology, acceptance by customers of the ABTS systems shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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